



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Chuen Rong Leu et al.
Assignee: Bridge Semiconductor Corporation
Title: METHOD OF MAKING A SEMICONDUCTOR CHIP
ASSEMBLY WITH AN EMBEDDED METAL PILLAR
Serial No.: 10/719,823 Filed: November 21, 2003
Examiner: Dang, P. Group Art Unit: 2818
Atty. Docket No.: BDG024-1

COMMISSIONER FOR PATENTS
P.O. Box 1450
Alexandria, VA 22313-1450

AMENDMENT AFTER ALLOWANCE

Dear Sir:

Please amend the application as follows.

The Specification Amendments begin on page 2.

The Remarks begin on page 3.